

### REMARKS

Claims 1 and 3-8 currently remain in the application. Claims 2 and 9 have been canceled and claims 1 and 8 are herein amended.

The editorial error in the description of the drawings, pointed out by the Examiner in Paragraph 1 of the Official Letter, has been corrected.

Claims 6 and 7 were rejected under 35 U.S.C. 112 in Paragraph 3 of the Official Letter. The Examiner is requested, however, to reconsider the rejection because although these claims include a Markush group while depending from claim 5 which also includes a Markush group, the Markush groups in claims 6 and 7 are strictly subgroups of the Markush group in claim 5. In other words, the scopes of claims 6 and 7 cannot be, and are not, greater than the scope of claim 5 and are within the scope of claim 5. Thus, it is believed that the dependency of claims 6 and 7 is proper.

Claims 1 and 3-8 were rejected under 35 U.S.C. 112. Independent claims 1 and 8 have therefore been amended at least in part in response to this rejection. The additional limitations that have been introduced are clearly supported by the specification and hence are believed to be enterable, besides obviating the Examiner's reasons for the rejection under 35 U.S.C. 112.

Claims 1-9 were rejected under 35 U.S.C. 102 as being anticipated by Tsujimoto. With independent claims 1 and 8 amended herein as explained above, however, it is believed that the Examiner's rejection has been overcome basically because Tsujimoto relates to a different technology and does not disclose or hint at the present invention as now narrowly defined by amended independent claims 1 and 8, including the limitation that the center line average roughness of the adhesive surface is substantially on the order of  $0.1\mu\text{m}$  when the peeling sheet is peeled from the base sheet.

Tsujimoto relates to the technology of die bonding and an adhesive tape for fastening a wafer for dicing. There is absolutely no mention of polishing of the wafer or its substrate, much less a requirement on the surface roughness when the peeling sheet is peeled off. In short, Tsujimoto does not disclose the present invention and it is believed that the present invention will not be found to be obvious in view of Tsujimoto even by a person skilled in the relevant art.

It is therefore believed that the application is now in condition for allowance.

Respectfully submitted,

A handwritten signature in black ink, appearing to read 'Kenichi Nishimura', is written over the printed name.

Kenichi Nishimura

Registration No. 29,093

June 23, 2005

BEYER WEAVER & THOMAS, LLP

500 12th Street, Suite 200

Oakland, California 94607

Telephone: (510) 663-1100

Telefax: (510) 663-0920